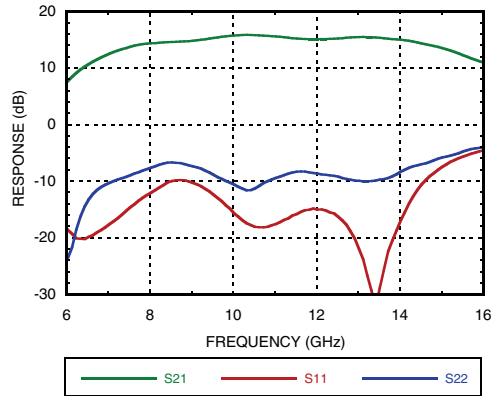
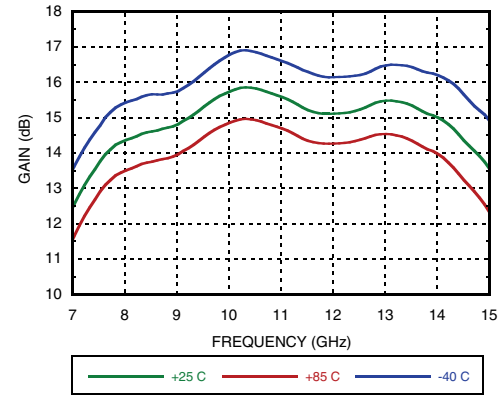
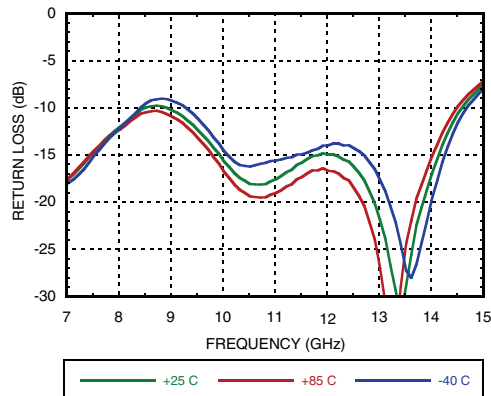
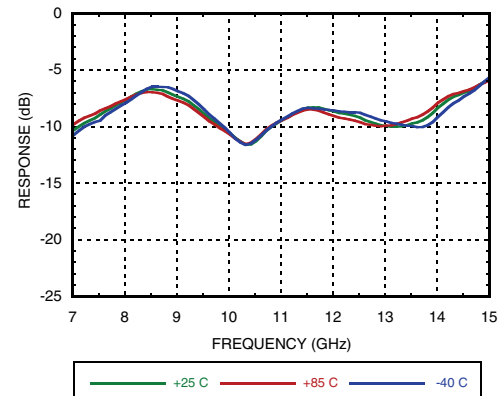
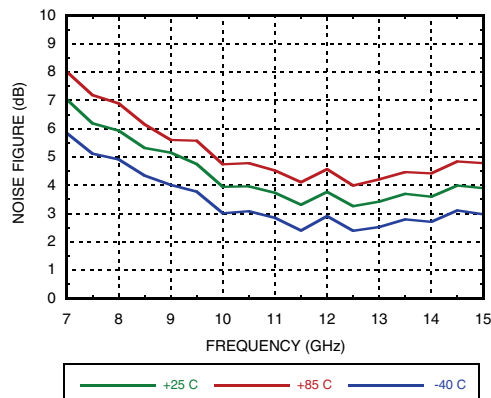
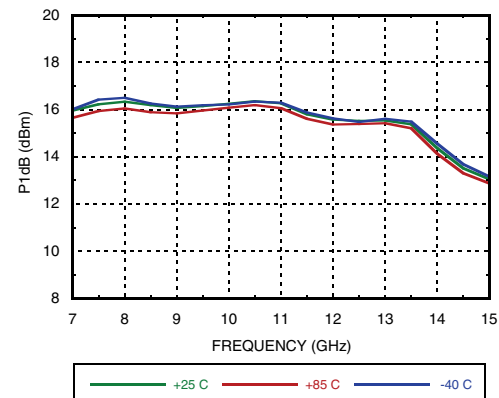
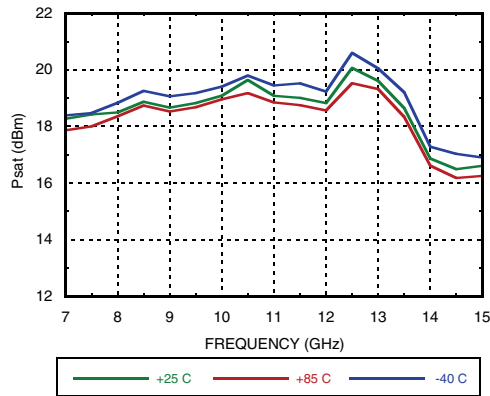
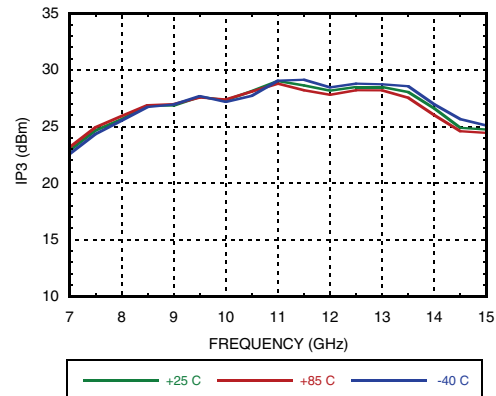
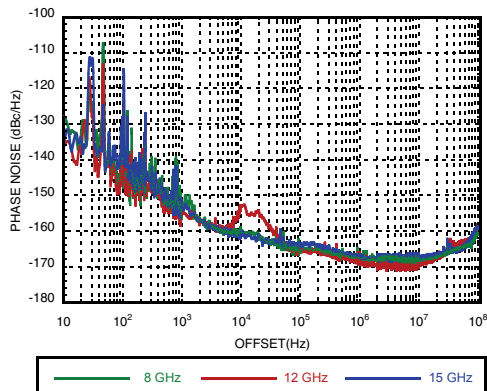
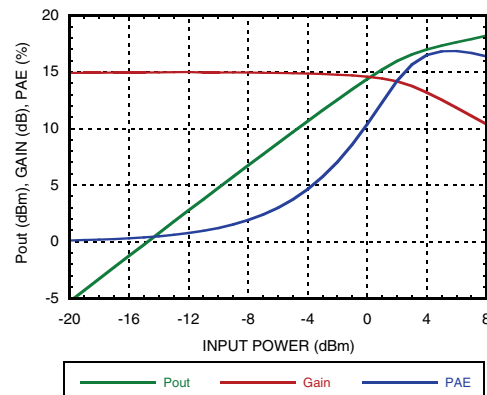
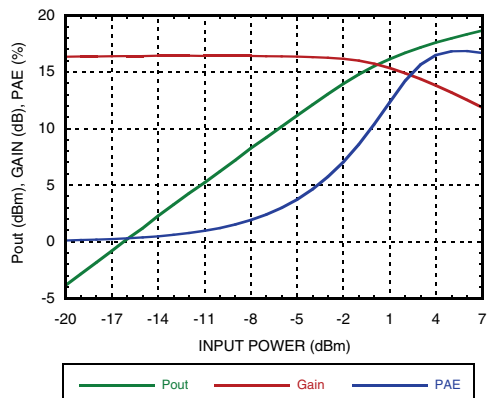
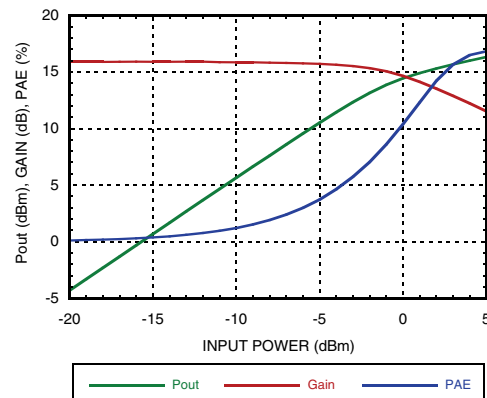
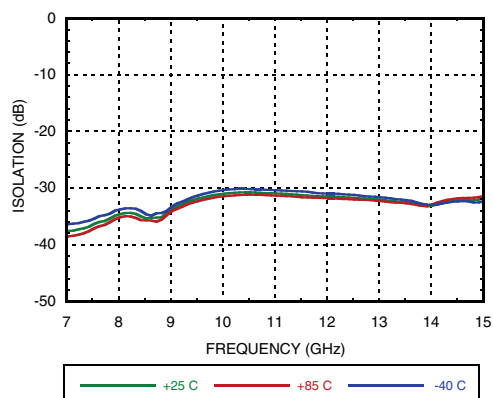


**HBT GAIN BLOCK
MMIC AMPLIFIER, 7 - 15 GHz**
Gain & Return Loss

Gain vs. Temperature

Input Return Loss vs. Temperature

Output Return Loss vs Temperature

Noise Figure vs. Temperature

P1dB vs. Temperature


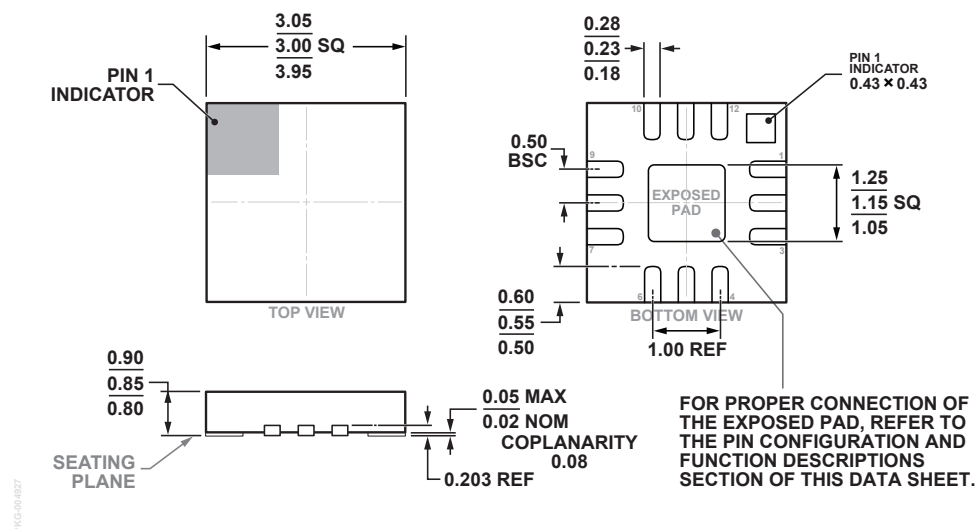
**HBT GAIN BLOCK
MMIC AMPLIFIER, 7 - 15 GHz**
Psat vs. Temperature

Output IP3 vs Temperature

Phase Noise @ Pin=0 dBm

Power Compression @ 8 GHz

Power Compression @ 11 GHz

Power Compression @ 14 GHz


**HBT GAIN BLOCK
MMIC AMPLIFIER, 7 - 15 GHz**
Reverse Isolation

Absolute Maximum Ratings

Drain Bias Voltage	6 Vdc
RF Input Power (RFIN)	+12 dBm
Channel Temperature	150 °C
Continuous P _{diss} (T=85 °C) (derate 7.87 mW/ °C Above +85 °C)	512 mW
Thermal Resistance (channel to ground paddle)	127 °C/W
Storage Temperature	-65 to 150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

**HBT GAIN BLOCK
MMIC AMPLIFIER, 7 - 15 GHz**
Outline Drawing


12-Lead Lead Frame Chip Scale Package [LFCSP]
3 mm × 3 mm Body and 0.85 mm Package Height
(CP-12-10)

Dimensions shown in millimeters

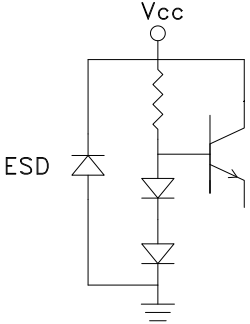
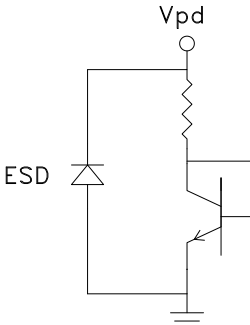
Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating ^[2]	Package Marking ^[1]
HMC3653LP3BE	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1	H3653 XXXX

[1] 4-Digit lot number XXXX

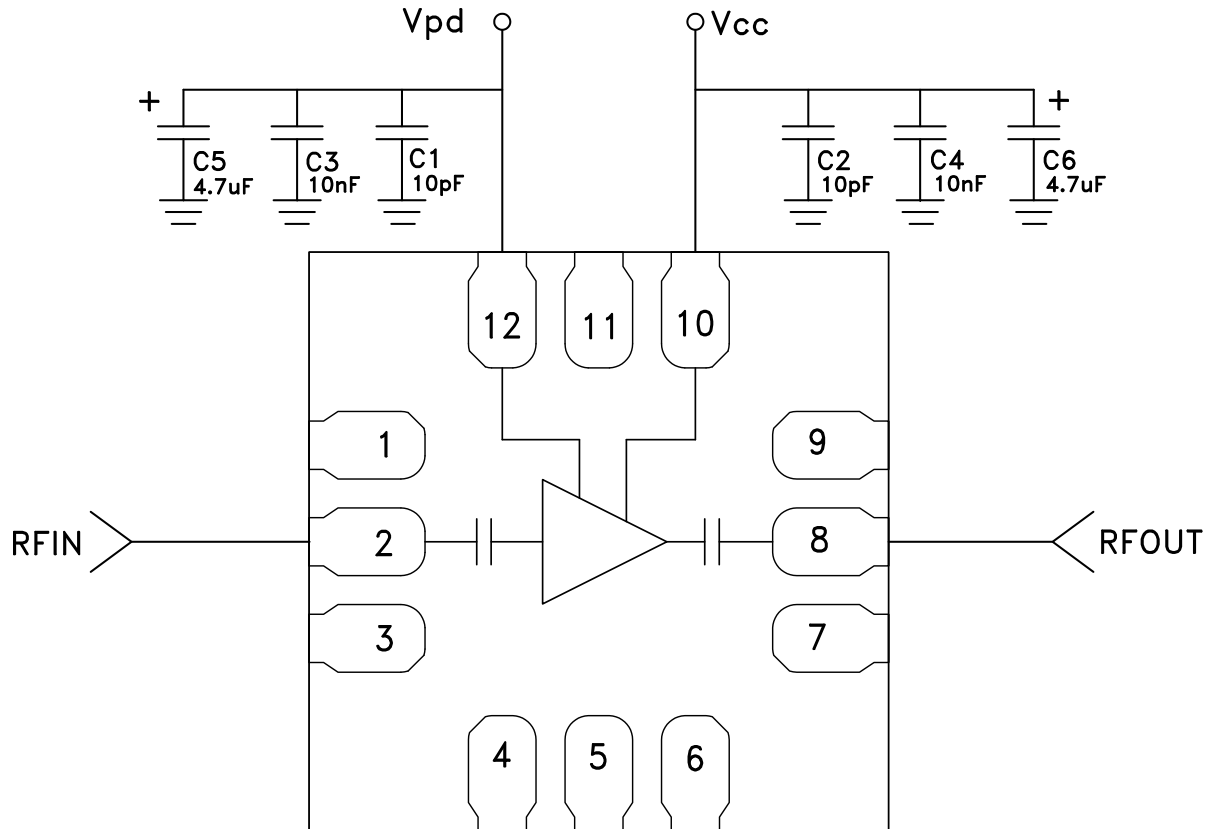
[2] Max peak reflow temperature of 260 °C

**HBT GAIN BLOCK
MMIC AMPLIFIER, 7 - 15 GHz**
Pin Descriptions

Pid Number	Function	Description	Interface Schematic
1, 3, 4, 5, 6, 7, 9, 11	NC	No connection necessary. These pins may be connected to RF/DC ground. Performance will not be affected.	
2	RFIN	This pin is AC coupled and matched to 50 Ohms.	RFIN ○ — —
8	RFOUT	This pin is AC coupled and matched to 50 Ohms.	— — ○ RFOUT
10	Vcc	Power supply voltage for the amplifier	
12	Vpd	Power Control Pin for proper control bias	
GND Paddle	GND	Ground Paddle must be connected to RF/DC ground.	

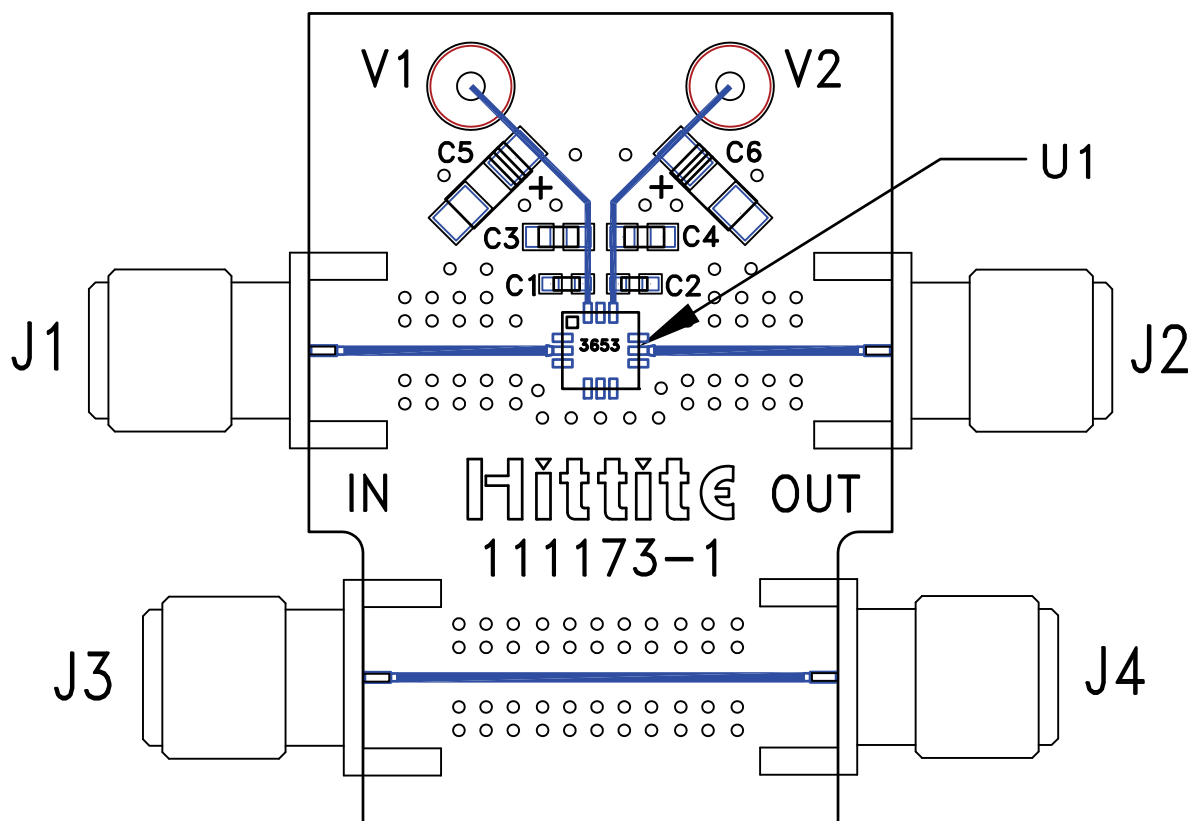
**HBT GAIN BLOCK
MMIC AMPLIFIER, 7 - 15 GHz**

Application Circuit



**HBT GAIN BLOCK
MMIC AMPLIFIER, 7 - 15 GHz**

Evaluation PCB



**List of Material for Evaluation PCB 113589-HMC3653LP3B-
rev D [1]**

Item	Description
J1, J4	PCB Mount SMA RF Connector
C1 - C2	10 pF Capacitor, 0402 Pkg.
C3 - C4	10000 pF Capacitor, 0603 Pkg.
C5 - C6	4.7 uF Capacitor, Tantalum.
U1	HMC3653LP3BE
PCB [2]	111173-1 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350 or Arlon 25FR

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Analog Devices upon request.